Amendments to the Claims:

The listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended). A micro leadframe package comprising:

a semiconductor chip;

a micro leadframe (MLF) having upper and lower surfaces, and comprising a die pad on which the semiconductor chip is mounted via adhesive means, leads formed along the outer sides of the die pad; and tie bars for supporting four corners of the die pad wherein the die pad, the leads, and the tie bars have an oblique etching portion;

wires for connecting the semiconductor chip with the leads of the MLF; and

an epoxy molding compound (EMC) for encapsulating the semiconductor chip, the MLF, and the wires,

wherein an etching solution and an etching method used on the upper surface of the MLF are the same as those used on the bottom surface of the MLF.

Claim 2 (Original). The micro leadframe package of claim 1, wherein a dimple is formed on the die pad of the MLF for increasing the attachment strength between the micro leadframe package and the EMC.

Claim 3 (Currently Amended). The micro leadframe package of claim 2, wherein ~~the~~ a plurality of the dimples are formed along four edges of the die pad.

Claim 4 (Original). The micro leadframe package of claim 1, wherein dimples are formed on the leads of the MLF for increasing the attachment strength between the micro leadframe package and the EMC.

Claim 5 (Original). The micro leadframe package of claim 1, wherein dimples are formed on the tie bars of the MLF for increasing the attachment strength between the micro leadframe package and the EMC.

Claim 6 (Original). The micro leadframe package of claim 1, wherein holes for firm solder connection are formed at the tips of the leads which are encapsulated by the EMC.

Claim 7 (Original). The micro leadframe package of claim 6, wherein the diameter of the holes for firm solder connection ranges from 50% to 95% of the width of the leads.

Claim 8 (Original). The micro leadframe package of claim 1, wherein the size of the oblique etching portion in a bottom surface of the MLF is greater than that of an upper surface.

Claim 9 (Original). The micro leadframe package of claim 8, wherein the size of the oblique etching portion in the bottom surface of the MLF is greater than that of the upper surface by about 1 – 10%.

Claim 10 (Original). The micro leadframe package of claim 1, wherein the die pad, the leads, and the tie bars are coplanar after being encapsulated by the EMC, and are exposed outward.

Claim 11 (Canceled).